ABSTRACT

Device Manufacturing Method and Device Manufactured Thereby

A device manufacturing method comprising the steps of:

providing a first substrate having first and second surfaces;

patterning said first surface of said substrate with at least one reversed alignment marker;

providing a protective layer over said alignment marker(s);

bonding said first surface of said first substrate to a second substrate;

locally etching said first substrate as far as said protective layer to form a trench around the or each reversed alignment marker; and

forming at least one patterned layer on said second surface using a lithographic projection apparatus having a front-to-backside alignment system whilst aligning said substrate to the alignment markers revealed in the or each trench.

Fig. 8